

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
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EPAS ID: PAT4250340

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
MIHIR A. OKA	01/03/2017
KEN P. HACKENBERG	01/19/2017
VIJAY KRISHNAN (VIJAY) SUBRAMANIAN	01/04/2017
NEHA M. PATEL	01/21/2017
NACHIKET R. RARAVIKAR	01/03/2017
RECEIVING PARTY DATA	
Name:	INTEL CORPORATION
Street Address:	2200 MISSION COLLEGE BOULEVARD
City:	SANTA CLARA
State/Country:	CALIFORNIA
Postal Code:	95054
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	15394460
CORRESPONDENCE DATA	
Fax Number:	
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
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Correspondent Name:	BLAKELY SOKOLOFF TAYLOR & ZAFMAN LLP
Address Line 1:	1279 OAKMEAD PARKWAY
Address Line 4:	SUNNYVALE, CALIFORNIA 94085
ATTORNEY DOCKET NUMBER:	42P98815
NAME OF SUBMITTER:	ESTIVEN ROJO
SIGNATURE:	/ESTIVEN ROJO/
DATE SIGNED:	01/30/2017
Total Attachments: 10	
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ASSIGNMENT

In consideration of good and valuable consideration, the receipt of which is hereby acknowledged, we, the undersigned inventor(s):

**Mihir A. OKA, Ken P. HACKENBERG, Vijay Krishnan (Vijay) SUBRAMANIAN,
Neha M. PATEL, and Nachiket R. RARAVIKAR**

hereby sell, assign, and transfer to:

Intel Corporation

a corporation of Delaware, having a principal place of business at 2200 Mission College Boulevard, Santa Clara, California, 95054 USA ("Assignee"), and its successors, assigns, and legal representatives, the entire right, title, and interest for the United States and all other countries, in and to any and all inventions and improvements that are disclosed in the application for the patent entitled:

**SINTERED SOLDER FOR FINE PITCH FIRST-LEVEL INTERCONNECT (FLI)
APPLICATIONS**

(I hereby authorize and request any attorney having appropriate authority from the assignee to insert on the designated lines below, the filing date and application number of said application when known.)

which was filed on December 29, 2016 as
US Application Number 15/394,460 and
COUNTRY or International Office

which has been executed by the undersigned prior hereto or concurrently herewith on the date(s) indicated below.

and in and to said application and all Additional Applications, and all other patent applications that have been or shall be filed in the United States and all other countries and international filing offices on any of said inventions and improvements; and in and to all original and reissued patents that have been or shall be issued in the United States and all other countries and international filing offices on said inventions and improvements; and in and to all rights of priority resulting from the filing of said applications; as used herein "Additional Applications" includes but is not limited to design, utility, utility model, divisional, continuing, continuation-in-part, substitute, renewal, reissue, and national phase applications on said inventions and improvements;

and agree that said Assignee may apply for and receive a patent or patents for said inventions and improvements in its own name; and that, when requested, without charge to, but at the expense of, said Assignee, its successors, assigns, and legal representatives, to carry out in good faith the intent and purpose of this Assignment, the undersigned will execute all Additional Applications, and all other patent applications on any and all said inventions and improvements; execute all rightful oaths, assignments, powers of attorney, and other papers; communicate to said Assignee, its successors, assigns, and legal representatives all facts known to the undersigned relating to said inventions and improvements and

the history thereof; and generally assist said Assignee, its successors, assigns, or legal representatives in securing and maintaining proper patent protection for said inventions and improvements and for vesting title to said inventions and improvements, and all applications for patents and all patents on said improvements, in said Assignee, its successors, assigns, and legal representatives; and

covenant with said Assignee, its successors, assigns, and legal representatives that no assignment, grant, mortgage, license, or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.

Mihir A. Oka

Mihir A. OKA

January 03, 2017

Date signed

Ken P. HACKENBERG

Date signed

Vijay Krishnan (Vijay) SUBRAMANIAN

Date signed

Neha M. PATEL

Date signed

Nachiket R. RARAVIKAR

Date signed

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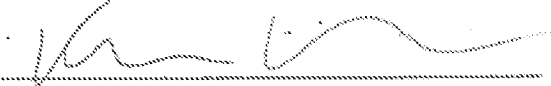
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_____ Mihir A. OKA	_____ Date signed
 _____ Ken P. HACKENBERG	<u>01/19/2017</u> _____ Date signed
_____ Vijay Krishnan (Vijay) SUBRAMANIAN	_____ Date signed
_____ Neha M. PATEL	_____ Date signed
_____ Nachiket R. RARAVIKAR	_____ Date signed

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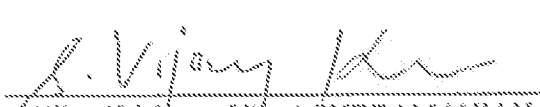
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Date signed

N. M. Patel
Neha M. PATEL

1/21/17
Date signed

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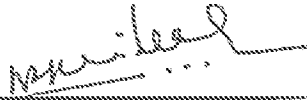
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----- Neha M. PATEL -----	----- Date signed -----
-----  ----- Nachiket R. RARAVIKAR	----- Jan 3, 2017 ----- Date signed